



Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	292	YES
×	2	22	0.55	2	NOT
□	3	31	0.80	2	NOT
◇	4	40	1.02	56	YES
×	5	126	3.20	2	NOT

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B		
LAYER TOP, BOTTOM	Impedance	Trace Width	Trace Separation	Ground Separation	
	50 Ohms	26 mils	N/A	6 mils	
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B		
LAYER TOP, BOTTOM	Impedance	Trace Width	Trace Separation	Ground Separation	
	90 Ohms	14.5 mils	6 mils	6 mils	
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B		
LAYER TOP, BOTTOM	Impedance	Trace Width	Trace Separation	Ground Separation	
	100 Ohms	10 mils	6 mils	6 mils	

1.061 MM +/-10%

LAYER 1 LT6 TOP

18 UM CU + 12.5 UM PLATING (30.5 UM)

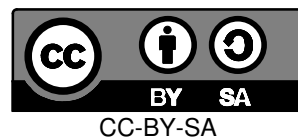
CORE

1.0 MM CORE FR-4 LG 135 INCLUDING COPPER

LAYER 4 LT6 BOTTOM

18 UM CU + 12.5 UM PLATING (30.5 UM)

1. PRINTED CIRCUIT BOARD MADE FROM NEMA GRADE FR-4 TO 135 EPOXY LAMINATE WITH 18 UM COPPER PLATING AND 1 MM THICKNESS.
2. ALL DIMENSIONS ARE GIVEN IN MILLIMETERS EXCEPT TRACE WIDTH/SPACE.
3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE WHITE SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY.  
EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSCREEN BOARD USING BLACK INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
  - \* 2 COPPER LAYERS
  - \* 1 MM BOARD THICKNESS
  - \* REQUIRES TOP AND BOTTOM SIDE SILKSCREENS



The Domino Team may make changes to specifications and product descriptions at any time, without notice.

Component Assembly CMP (.ASC) Rev. D